SDAS187A – APRIL 1982 – REVISED DECEMBER 1994

 Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

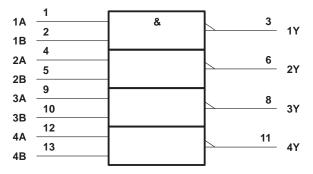
## description

These devices contain four independent 2-input positive-NAND gates. They perform the Boolean functions  $Y = \overline{A \cdot B}$  or  $Y = \overline{A + B}$  in positive logic.

The SN54ALS00A and SN54AS00 are characterized for operation over the full military temperature range of  $-55^{\circ}$ C to  $125^{\circ}$ C. The SN74ALS00A and SN74AS00 are characterized for operation from 0°C to 70°C.

FUNCTION TABLE (each gate)								
INP	UTS	OUTPUT						
Α	В	Y						
Н	Н	L						
L	Х	н						
Х	L	н						

logic symbol<sup>†</sup>



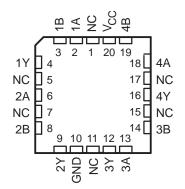
<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for the D, J, and N packages.

SN54ALS00A, SN54AS00 ... J PACKAGE SN74ALS00A, SN74AS00 ... D OR N PACKAGE (TOP VIEW)

1A [ 1B [ 1Y [ 2A [ 2B [ 2Y [ GND [	1 2 3 4 5 6 7	D	14 13 12 11 10 9 8		V <sub>CC</sub> 4B 4A 4Y 3B 3A 3Y					

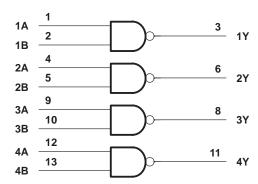
# SN54ALS00A, SN54AS00 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

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#### logic diagram (positive logic)



Pin numbers shown are for the D, J, and N packages.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage, V <sub>CC</sub>	
Input voltage, V <sub>1</sub>	7 V
Operating free-air temperature range, T <sub>A</sub> : SN54ALS00A	-55°C to 125°C
SN74ALS00A	0°C to 70°C
Storage temperature range	-65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### recommended operating conditions

		SN54ALS00A			SN	UNIT			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V	
VIH	High-level input voltage	2			2			V	
Ma	Low-level input voltage			0.8‡			0.8	V	
VIL				0.7§					
IOH	High-level output current			-0.4			-0.4	mA	
IOL	Low-level output current			4			8	mA	
TA	Operating free-air temperature	-55		125	0		70	°C	

<sup>‡</sup> Applies over temperature range – 55°C to 70°C

§ Applies over temperature range 70°C to 125°C



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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST O	TEST CONDITIONS		154ALS0	0A	SN74ALS00A			UNIT
PARAMETER	TEST CONDITIONS		MIN	TYP†	MAX	MIN	TYP†	MAX	UNIT
VIK	V <sub>CC</sub> = 4.5 V,	lı = -18 mA			-1.2			-1.5	V
VOH	$V_{CC} = 4.5 V$ to 5.5 V,	$I_{OH} = -0.4 \text{ mA}$	V <sub>CC</sub> –	2		V <sub>CC</sub> -2	2		V
Ve	V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 4 mA		0.25	0.4		0.25	0.4	V
VOL	VCC = 4.5 V	I <sub>OL</sub> = 8 mA					0.35	0.5	v
Ц	V <sub>CC</sub> = 5.5 V,	$V_{I} = 7 V$			0.1			0.1	mA
Ιн	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 2.7 V			20			20	μΑ
١ <sub>١L</sub>	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 0.4 V			-0.1			-0.1	mA
10‡	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.25 V	-20		-112	-30		-112	mA
ІССН	V <sub>CC</sub> = 5.5 V,	$V_{I} = 0$		0.5	0.85		0.5	0.85	mA
ICCL	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 4.5 V		1.5	3		1.5	3	mA

<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

<sup>‡</sup>The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

#### switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	то (оитрит)	V <sub>C</sub> C <sub>L</sub> R <sub>L</sub> T <sub>A</sub> SN54AI		UNIT		
			MIN	MAX	MIN	MAX	
<sup>t</sup> PLH	A or B	V	3	15	3	11	
<sup>t</sup> PHL	AUB	T	2	9	2	8	ns

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



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### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage, V <sub>CC</sub>	
Operating free-air temperature range, T <sub>A</sub> : SN54AS00	
SN74AS00	0°C to 70°C
Storage temperature range	65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### recommended operating conditions

		SN54AS00		S				
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	V
ЮН	High-level output current			-2			-2	mA
IOL	Low-level output current			20			20	mA
TA	Operating free-air temperature	-55		125	0		70	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		SN	SN54AS00			SN74AS00		
PARAMETER			MIN	гүр‡	MAX	MIN	typ‡	MAX	UNIT
VIK	V <sub>CC</sub> = 4.5 V,	lı = -18 mA			-1.2			-1.2	V
VOH	$V_{CC} = 4.5 V \text{ to } 5.5 V,$	$I_{OH} = -2 \text{ mA}$	V <sub>CC</sub> -2			V <sub>CC</sub> -2	2		V
V <sub>OL</sub>	V <sub>CC</sub> = 4.5 V,	I <sub>OL</sub> = 20 mA		0.35	0.5		0.35	0.5	V
lj	V <sub>CC</sub> = 5.5 V,	$V_{I} = 7 V$			0.1			0.1	mA
IН	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 2.7 V			20			20	μΑ
١ <sub>١L</sub>	V <sub>CC</sub> = 5.5 V,	$V_{I} = 0.4 V$			-0.5			-0.5	mA
١ <sub>O</sub> §	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.25 V	-30		-112	-30		-112	mA
Іссн	V <sub>CC</sub> = 5.5 V,	$V_{I} = 0$		2	3.2		2	3.2	mA
ICCL	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 4.5 V		10.8	17.4		10.8	17.4	mA

<sup>‡</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

§ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

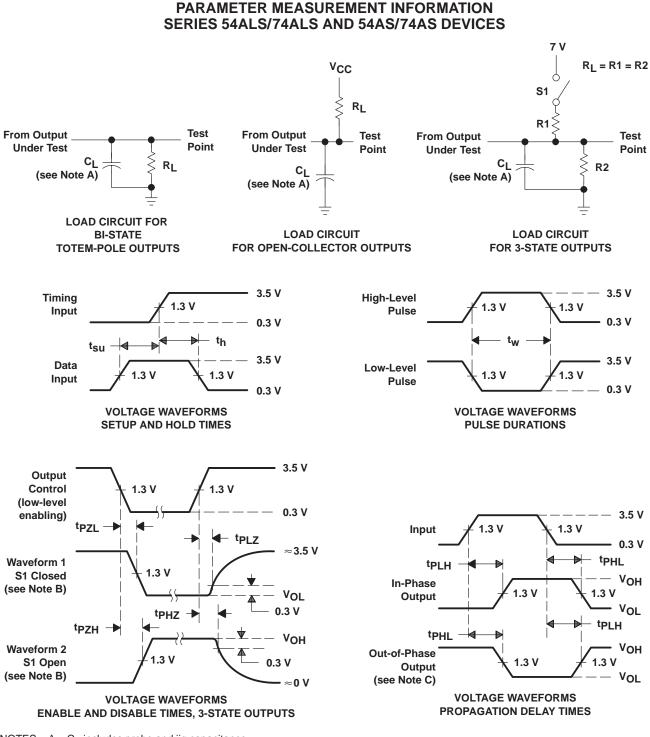
#### switching characteristics (see Figure 1)

PARAMETER	PARAMETER FROM (INPUT)	то (ОИТРИТ)	V <sub>C</sub> C <sub>L</sub> R <sub>L</sub> T <sub>A</sub>	UNIT			
			SN54	AS00	SN74/	AS00	
			MIN	MAX	MIN	MAX	
<sup>t</sup> PLH	A or B	V	1	5	1	4.5	ns
<sup>t</sup> PHL		Ť	1	5	1	4	115

<sup>¶</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



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NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR  $\leq$  1 MHz,  $t_{f}$  =  $t_{f}$  = 2 ns, duty cycle = 50\%.
- E. The outputs are measured one at a time with one transition per measurement.

#### Figure 1. Load Circuits and Voltage Waveforms



# PACKAGE OPTION ADDENDUM

6-Jun-2005

## **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finis	h MSL Peak Temp <sup>(3)</sup>
5962-86833012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
5962-8683301DA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/37001B2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
JM38510/37001BCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN54ALS00AJ	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN54AS00J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN74ALS00AD	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74ALS00ADBR	ACTIVE	SSOP	DB	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74ALS00ADBRE4	ACTIVE	SSOP	DB	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74ALS00ADE4	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74ALS00ADR	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74ALS00ADRE4	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74ALS00AN	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74ALS00AN3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI
SN74ALS00ANSR	ACTIVE	SO	NS	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74ALS00ANSRE4	ACTIVE	SO	NS	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74AS00D	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74AS00DE4	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74AS00DR	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74AS00DRE4	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74AS00N	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74AS00NE4	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74AS00NSR	ACTIVE	SO	NS	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74AS00NSRE4	ACTIVE	SO	NS	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SNJ54ALS00AFK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54ALS00AJ	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54ALS00AW	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54AS00FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54AS00J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC

<sup>(1)</sup> The marketing status values are defined as follows:





**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available. **OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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J (R-GDIP-T\*\*) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



MLCC006B - OCTOBER 1996

## FK (S-CQCC-N\*\*)

#### LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



# N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- $\triangle$  The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012 variation AB.



## MECHANICAL DATA

## PLASTIC SMALL-OUTLINE PACKAGE

#### 0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 $\bigcirc$ Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS \*\* 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G\*\*)

**14-PINS SHOWN** 

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



# **MECHANICAL DATA**

MSSO002E - JANUARY 1995 - REVISED DECEMBER 2001

## DB (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-150



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